

Wood Fiber Insulation (WFI)

I-BOND[®] MDI resins

I-BOND[®] WFI 4370	Low temperature curing MDI resin
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I-RELEASE[®] release agents

I-RELEASE[®] WFI 9162	<p>A water based, silicone free external release agent</p> <ul style="list-style-type: none">• designed to be sprayed at the inlet of continuous presses• a cost effective solution• reduces plant interruptions <p>Solids content: 20%</p>
I-RELEASE[®] WFI 9165	<p>A water based, silicone free external release agent</p> <ul style="list-style-type: none">• designed to be sprayed at the inlet of continuous presses• a cost effective solution• reduces plant interruptions <p>Solids content: 40%</p>